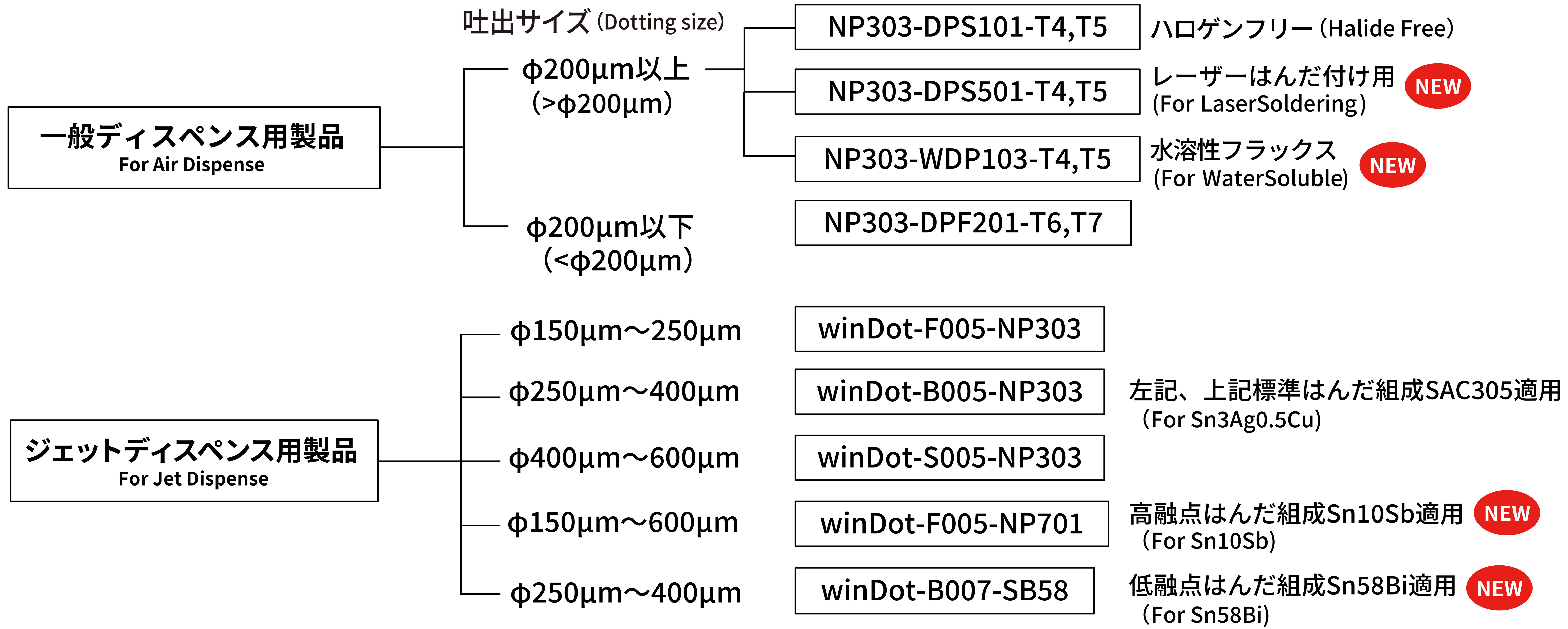
3D構造組立へ！微細ディスペンス用はんだペースト！

For 3D structural assembly! Solder paste for micro-dispensing!

ディスペンス用製品のラインアップ拡大 New solder paste for dispensing



winDot-F005-NP701 (ジェットディスペンス用) (forJet Dispensing)

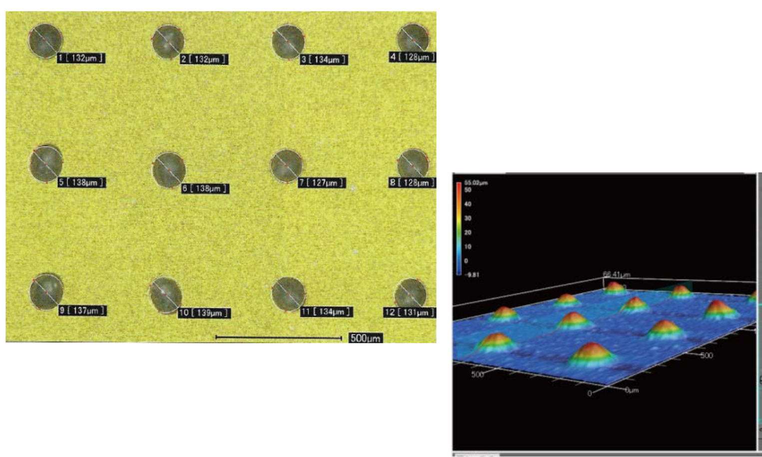
Jet Dispense 用はんだに高融点組成のはんだ (Sn10Sb) が新たに追加

High temperature solder(Sn10Sb) also added on line-up of Jet Dispense products

微細吐出の特性 Property of fine dispense

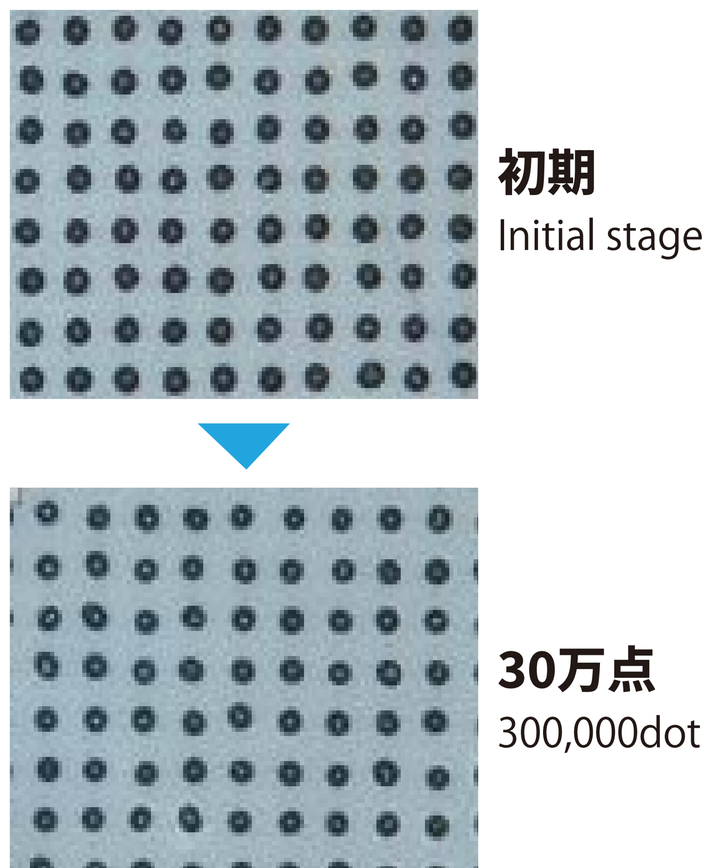
Type7ペーストでф200μm 以下の安定吐出を実現

Capable of dispensing ф200μm or less by Type7 paste!



連続吐出性能

Continuous dispensing performance



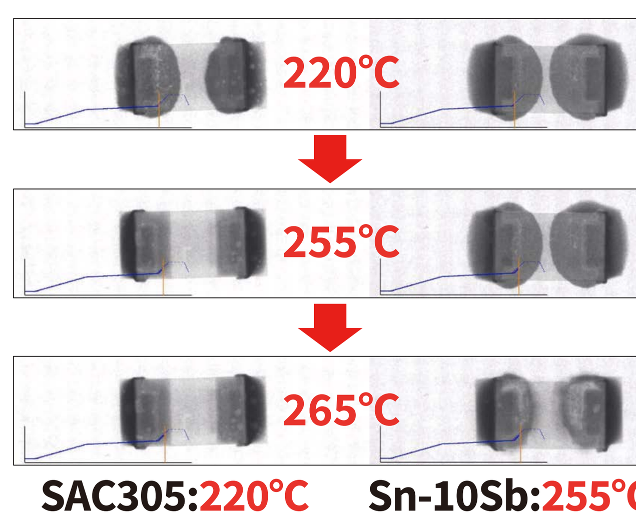
高融点はんだの特性 Property of high temperature solder

次工程での部品内部接合の再溶融防止に高融点はんだを適用

Apply high temperature solder to prevent from re-melting inside component at next process

溶融開始温度比較

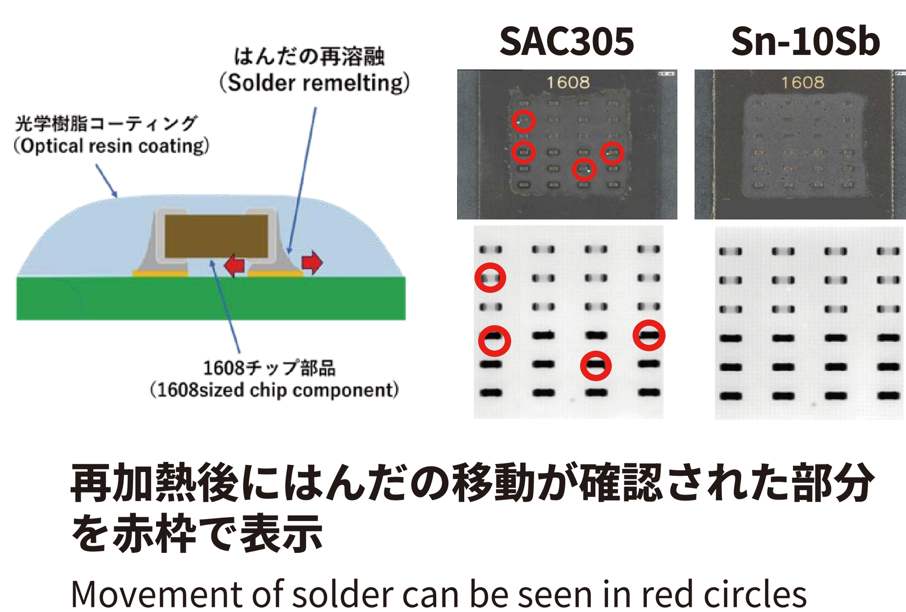
Melting temperature comparison



SAC305:220℃ Sn-10Sb:255℃

接合部の樹脂モールド後の再加熱によるはんだ再溶融挙動有無を確認

Check the re-melting after resin molding



再加熱後にはんだの移動が確認された部分を赤枠で表示

Movement of solder can be seen in red circles

NP303-WDP103-T5

(一般ディスペンス用：水溶性フラックス適用製品)

(Water soluble flux based product For Air Dispensing)

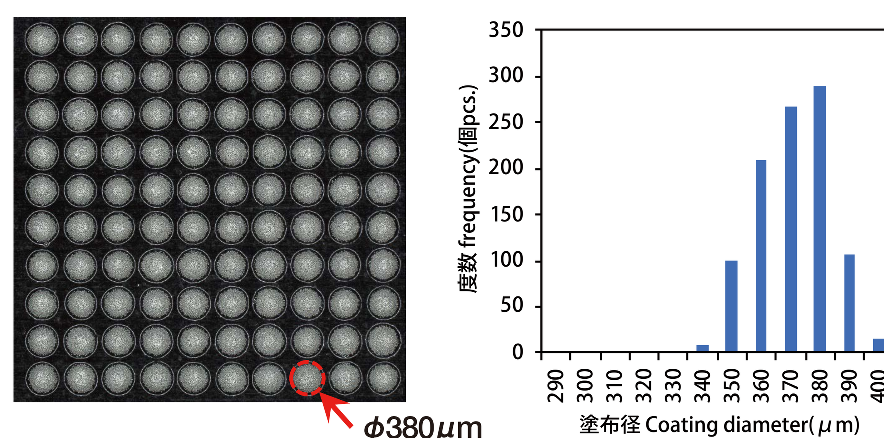
良好な吐出安定性と洗浄性

Excellent dispensing stability and cleanability

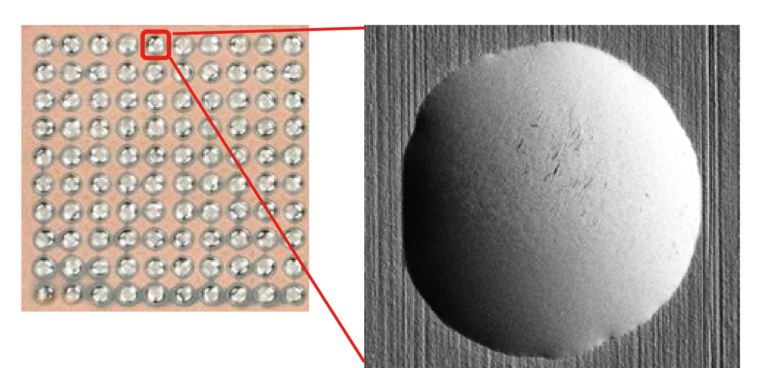
吐出性と洗浄性の確認結果 Test result of dotting performance and washability

60万点連続吐出時

At 600,000 points of continuous dispensing



洗浄後 After washing　**SEM観察** SEM observation



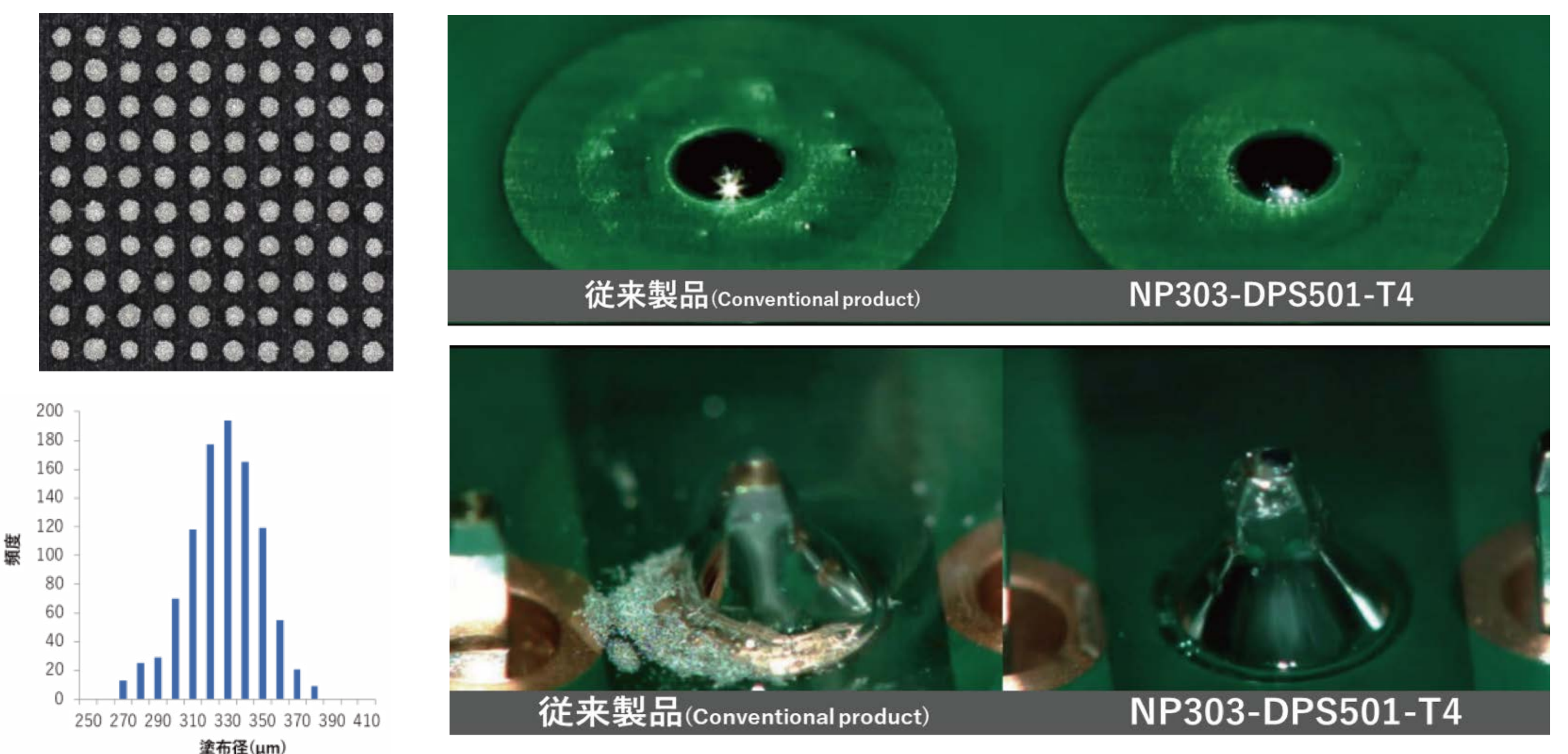
NP303-DPS501-T4

(一般ディスペンス用：レーザーはんだ付け対応)

(For normal dispense : applicable to laser soldering)

レーザー急加熱時のこぼれボール抑制で優れた凝集性

Excellent solderability with reduced solder ball outflow during rapid laser heating



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